(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
12 June 2003 (12.06.2003)

PCT

(10) International Publication Number
WO 03/049177 A3

(51) International Patent Classification[7]: H01L 21/56

(21) International Application Number: PCT/NL02/00797

(22) International Filing Date: 5 December 2002 (05.12.2002)

(25) Filing Language: Dutch

(26) Publication Language: English

(30) Priority Data:
1019514 7 December 2001 (07.12.2001) NL

(71) Applicant *(for all designated States except US)*: **FICO B.V.** [NL/NL]; Ratio 6, NL-6921 RW Duiven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **PETERS, Hendrikus, Johannes, Bernardus** [NL/NL]; Haaghweg 12, NL-6942 GP Didam (NL). **GAL, Wilhelmus, Gerardus, Jozef** [NL/NL]; Beekseweg 2, NL-7031 AX Kilder (NL). **VENROOIJ, Johannes, Lambertus, Gerardus, Maria** [NL/NL]; Brederode 18, NL-6922 BM Duiven (NL).

(74) Agent: **VAN DEN HEUVEL, Henricus, Theodorus**; Patentwerk B.V., P.O. Box 1514, NL-5200 BN 's-Hertogenbosch (NL).

(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

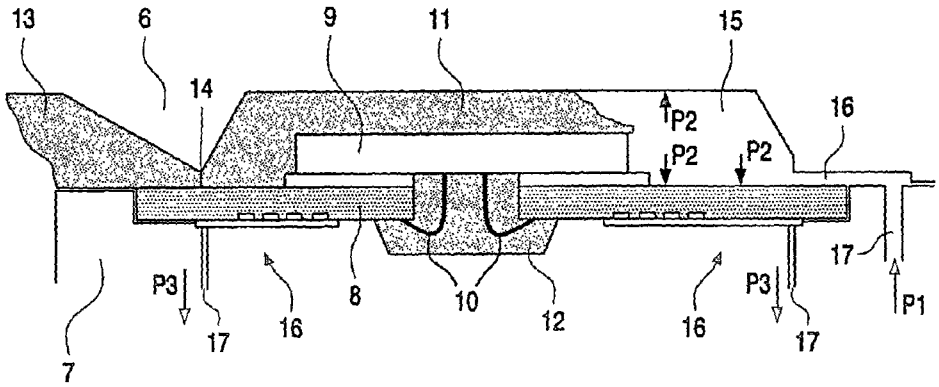
(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

(88) Date of publication of the international search report:
16 October 2003

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD AND DEVICE FOR ENCAPSULATING ELECTRONIC COMPONENTS WHILE EXERTING FLUID PRESSURE



(57) Abstract: The invention relates to a method for encapsulating electronic components, in particular semiconductors, by receiving a component for encapsulating between two mould halves displaceable relative to each other and feeding a liquid encapsulating material under overpressure by means of a transfer mechanism to at least one mould cavity arranged for this purpose, characterized in that during feeding of liquid encapsulating material to the mould cavity the part of the mould cavity not yet filled with encapsulating material is filled with a gas under overpressure. The invention also relates to a device for encapsulating electronic components.

WO 03/049177 A3